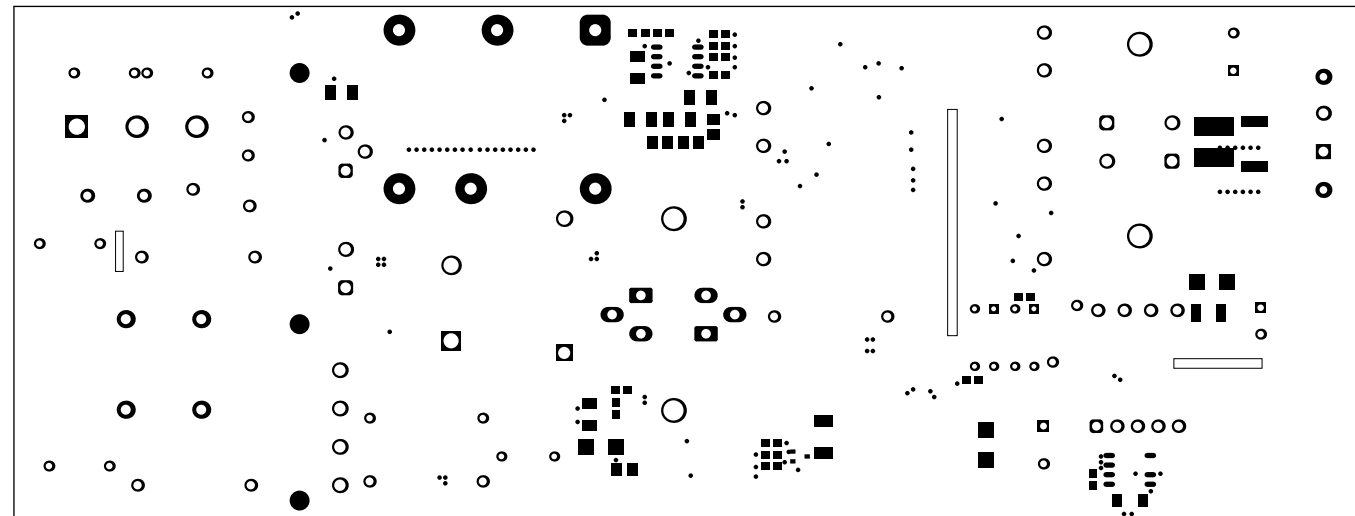
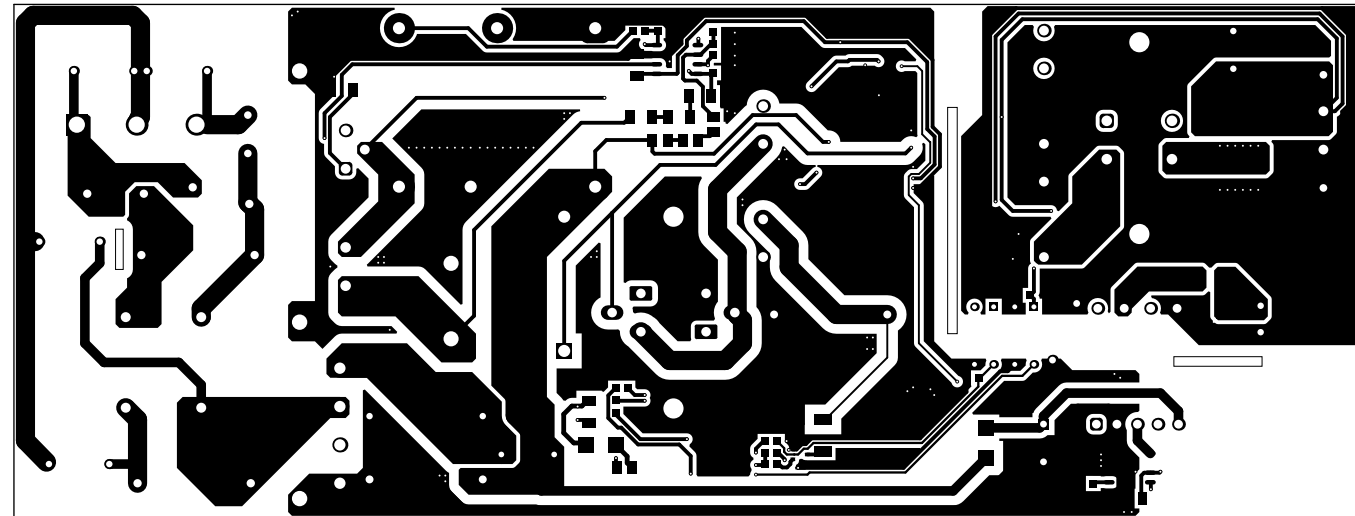


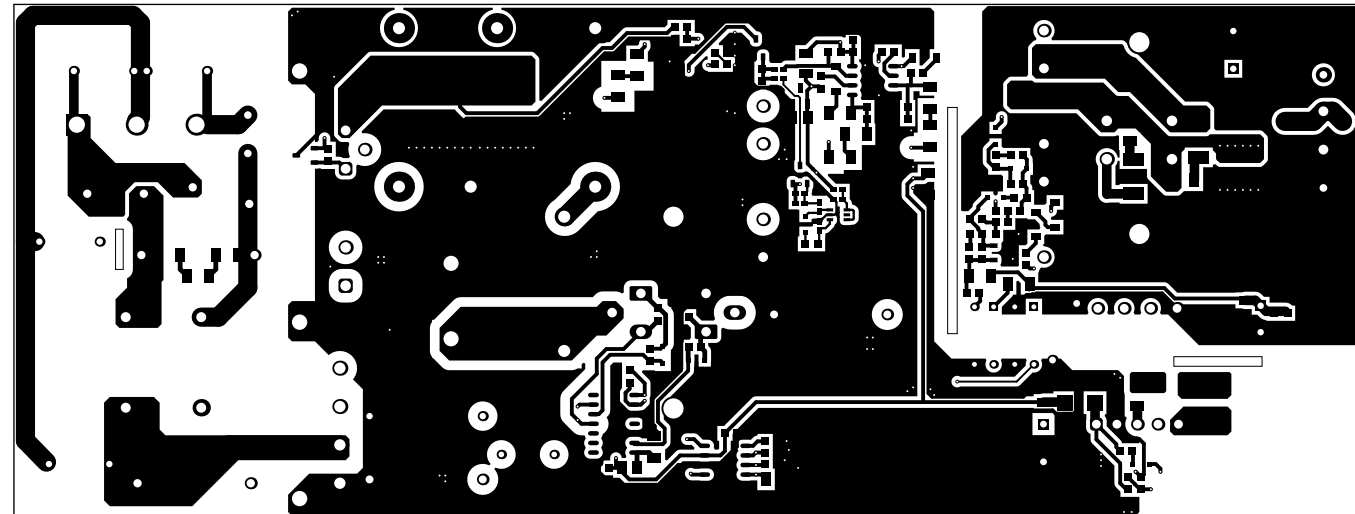
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 11/20/2017 5:18:48 PM		TEXAS INSTRUMENTS



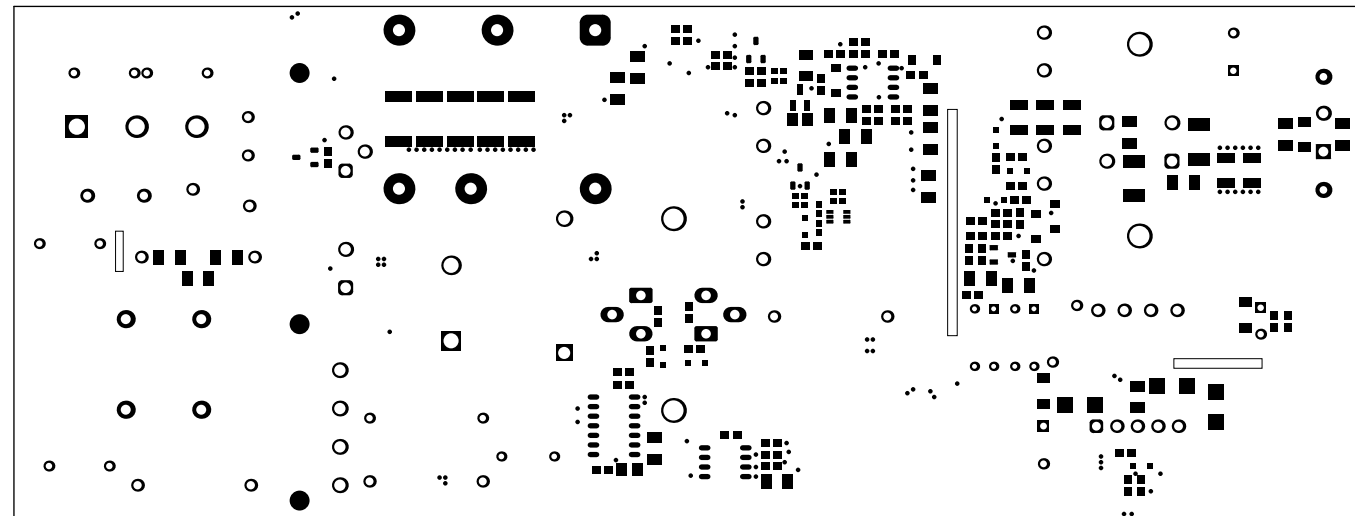
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 11/20/2017 5:18:50 PM	TEXAS INSTRUMENTS	



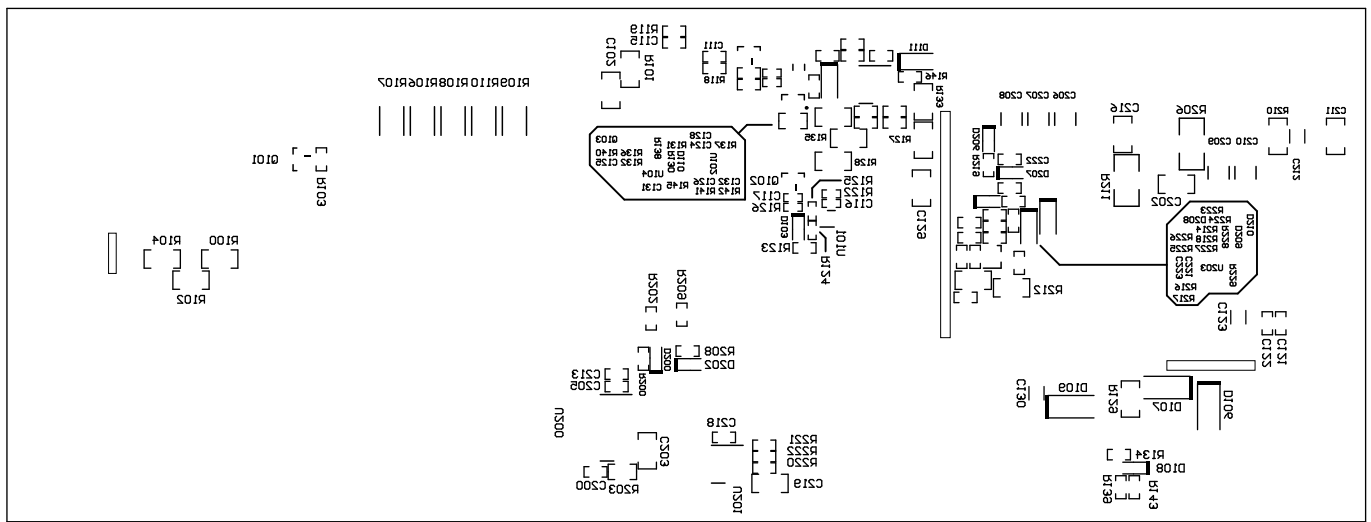
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 11/20/2017 5:18:51 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 11/20/2017 5:18:52 PM		TEXAS INSTRUMENTS

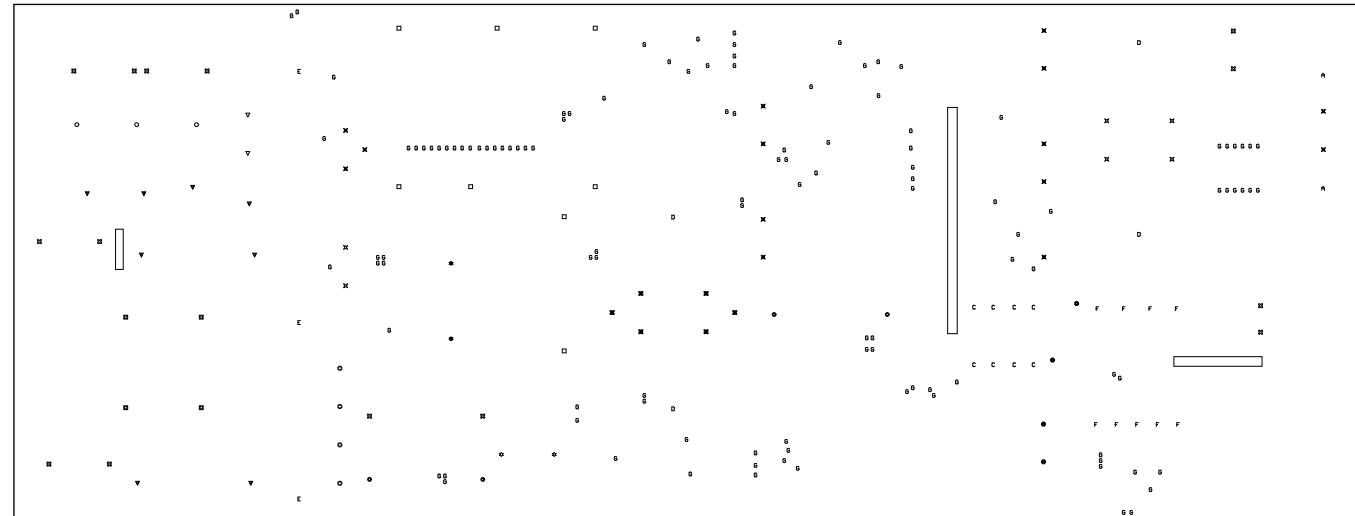


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/20/2017 5:18:54 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 11/20/2017 5:18:55 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
G	118	0.254mm (10.00mil)	PTH	Round	Top Layer - Bottom Layer	
C	8	0.650mm (25.59mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	0.750mm (29.53mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	14	0.850mm (33.47mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	
▽	2	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	
A	2	1.016mm (40.00mil)	PTH	Round	Top Layer - Bottom Layer	
○	4	1.050mm (41.34mil)	PTH	Round	Top Layer - Bottom Layer	
▽	8	1.100mm (43.31mil)	PTH	Round	Top Layer - Bottom Layer	
F	9	1.170mm (46.06mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	1.270mm (50.00mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	14	1.300mm (51.18mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	1.321mm (52.00mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	1.400mm (55.12mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	1.500mm (59.06mil)	PTH	Round	Top Layer - Bottom Layer	
□	8	1.600mm (62.99mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	2.000mm (78.74mil)	PTH	Round	Top Layer - Bottom Layer	
E	3	2.032mm (80.00mil)	PTH	Round	Top Layer - Bottom Layer	
○	3	2.150mm (84.65mil)	PTH	Round	Top Layer - Bottom Layer	
D	4	2.670mm (105.12mil)	PTH	Round	Top Layer - Bottom Layer	
	225 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 11/20/2017 5:18:56 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20694	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 11/20/2017 5:18:58 PM	TEXAS INSTRUMENTS	

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